

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	A
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20050026418 A1	20050203	17	Method of manufacturing semiconductor device	438/614		
2	<input type="checkbox"/>	<input type="checkbox"/>	US 20050026323 A1	20050203	27	Method of manufacturing a semiconductor device	438/106		
3	<input type="checkbox"/>	<input type="checkbox"/>	US 20040245648 A1	20041209	40	Bonding material and bonding method	257/772	257/778; 257/779; 438/108	
4	<input type="checkbox"/>	<input type="checkbox"/>	US 20040226744 A1	20041118	36	Module with built-in circuit component and method for producing the same	174/262		
5	<input type="checkbox"/>	<input type="checkbox"/>	US 20040214370 A1	20041028	17	Method for efficient capillary underfill	438/106		
6	<input type="checkbox"/>	<input type="checkbox"/>	US 20040171179 A1	20040902	15	Substrate mapping	438/15	257/E23.179	
7	<input type="checkbox"/>	<input type="checkbox"/>	US 20040166605 A1	20040826	34	Fabrication method of semiconductor integrated circuit device	438/106		
8	<input type="checkbox"/>	<input type="checkbox"/>	US 20040142551 A1	20040722	29	Semiconductor device and a method of manufacturing the same	438/612	257/E23.021	
9	<input type="checkbox"/>	<input type="checkbox"/>	US 20040130014 A1	20040708	29	Semiconductor device and its manufacturing method	257/678		
10	<input type="checkbox"/>	<input type="checkbox"/>	US 20040095707 A1	20040520	10	Method of forming a low inductance high capacitance capacitor	361/306.1		
11	<input type="checkbox"/>	<input type="checkbox"/>	US 20040082205 A1	20040429	10	Ic socket	439/73		